

Opportunities in hybrid bonding technologies – August 8, 2023

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INDUSTRY NEWS

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- STMicroelectronics begins volume production of PowerGaN devices for slimmer, cooler, and more efficient power products
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- ViTrox to Demonstrate Next-Generation Vision Inspection Systems at ELEXCON Shenzhen 2023!
- Advanced Packaging Inspection at SEMICON Taiwan 2023

Video of the day

Opportunities in hybrid bonding technologies.

David Kirsch discusses the success of the recently opened Materials Testing Center and the opportunities opening up with their hybrid bonding technologies. Kirsch also discusses their maskless imaging systems that make significant quality, time and cost savings.



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